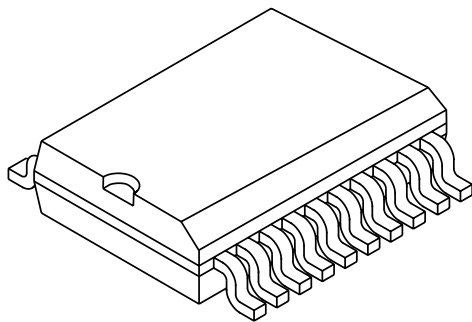


DATA SHEET



BZA109 9-fold ESD transient voltage suppressor

Product specification
Supersedes data of 1997 Oct 27
File under Discrete Semiconductors, SC01

1997 Dec 01

9-fold ESD transient voltage suppressor

BZA109

FEATURES

- ESD rating >8 kV, according to IEC1000-4-2
- SOT163-1 surface mount package
- Common anode configuration
- Non-clamping range 0.5 to 6.8 V
- Maximum non-repetitive peak reverse power dissipation: 25 W at $t_p = 1$ ms
- Maximum clamping voltage at peak pulse current: 10 V at $I_{ZSM} = 2.5$ A.

APPLICATIONS

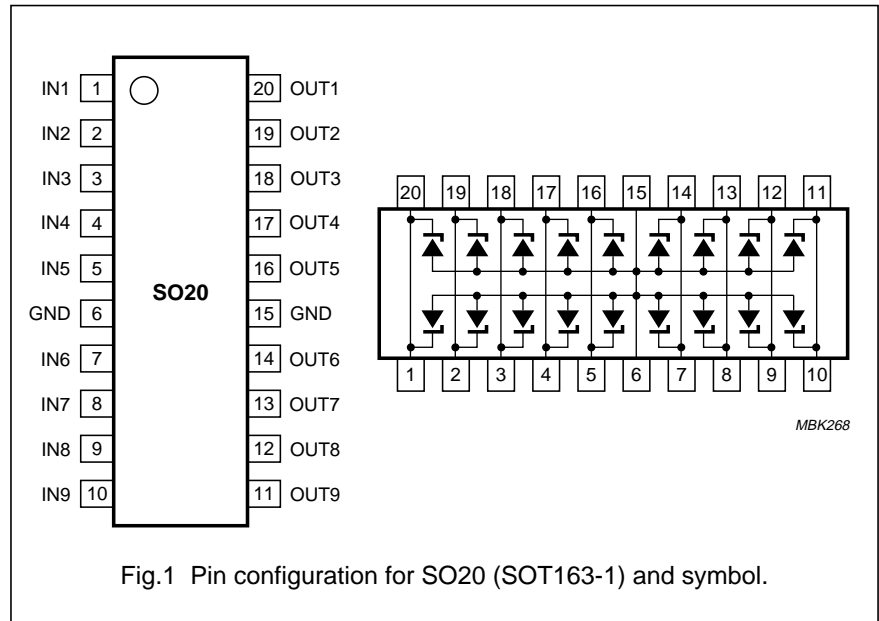
- For 9-bit wide undershoot/overshoot clamping and fast ESD transient suppression in:
 - Computers and peripherals
 - Audio and video equipment
 - Business machines
 - Communication systems
 - Medical equipment.

DESCRIPTION

9-fold monolithic transient voltage suppressor in an SO20; SOT163-1 surface mount package. The device is ideal in situations where board space is a premium.

PINNING

PIN	DESCRIPTION
1 to 5	input (IN1 to IN5)
6 and 15	common anode (GND)
7 to 10	input (IN6 to IN9)
11 to 14	output (OUT9 to OUT6)
16 to 20	output (OUT5 to OUT1)



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
I_Z	working current	$T_{amb} = 25$ °C	–	20	mA
I_F	continuous forward current	$T_{amb} = 25$ °C	–	100	mA
I_{FT}	feed-through current	$T_{amb} = 25$ °C; note 1	–	100	mA
I_{FSM}	non-repetitive peak forward current	$t_p = 1$ ms; square pulse	–	4.5	A
I_{ZSM}	non-repetitive peak reverse current	$t_p = 1$ ms; square pulse; see Fig.2	–	2.5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C; note 2; see Fig.3	–	1.25	W
P_{ZSM}	non-repetitive peak reverse power dissipation	$t_p = 1$ ms; square pulse; see Fig.4	–	25	W
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–65	+150	°C

Notes

1. Current is flowing from input to corresponding output.
2. One or more diodes loaded.

9-fold ESD transient voltage suppressor

BZA109

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	one or more diodes loaded	100	K/W

ELECTRICAL CHARACTERISTICS

 $T_j = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per diode						
V_Z	working voltage	$I_Z = 250\ \mu\text{A}$	6.4	6.8	7.2	V
V_F	forward voltage	$I_F = 100\ \text{mA}$	–	–	1.1	V
V_{ZSM}	non-repetitive peak reverse voltage	$I_{ZSM} = 2.5\ \text{A}; t_p = 1\ \text{ms}$	–	–	10	V
I_H	input high current	$V_{IN} = 5.25\ \text{V}$	–	–	0.5	μA
r_{dif}	differential resistance	$I_Z = 250\ \mu\text{A}$	–	–	100	Ω
S_Z	temperature coefficient of working voltage	$I_Z = 5\ \text{mA}$	–	3	–	mV/K
C_d	diode capacitance	see Fig.5 $V_R = 0; f = 1\ \text{MHz}$	–	–	200	pF
		$V_R = 5.25\ \text{V}; f = 1\ \text{MHz}$	–	–	100	pF

9-fold ESD transient voltage suppressor

BZA109

GRAPHICAL DATA

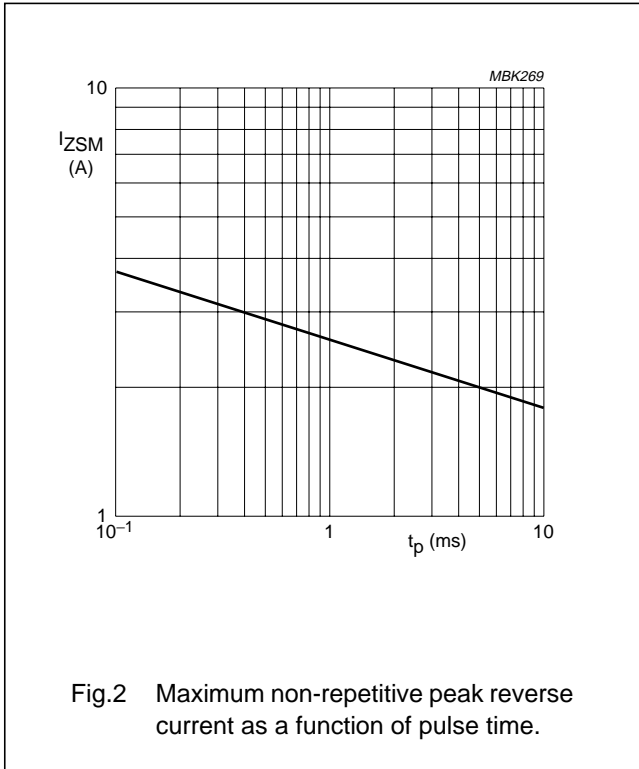
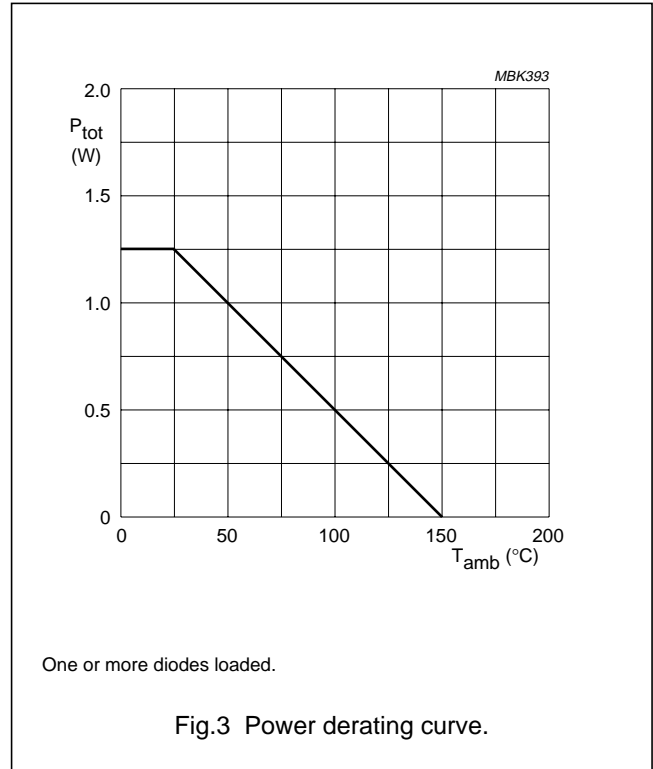


Fig.2 Maximum non-repetitive peak reverse current as a function of pulse time.



One or more diodes loaded.

Fig.3 Power derating curve.

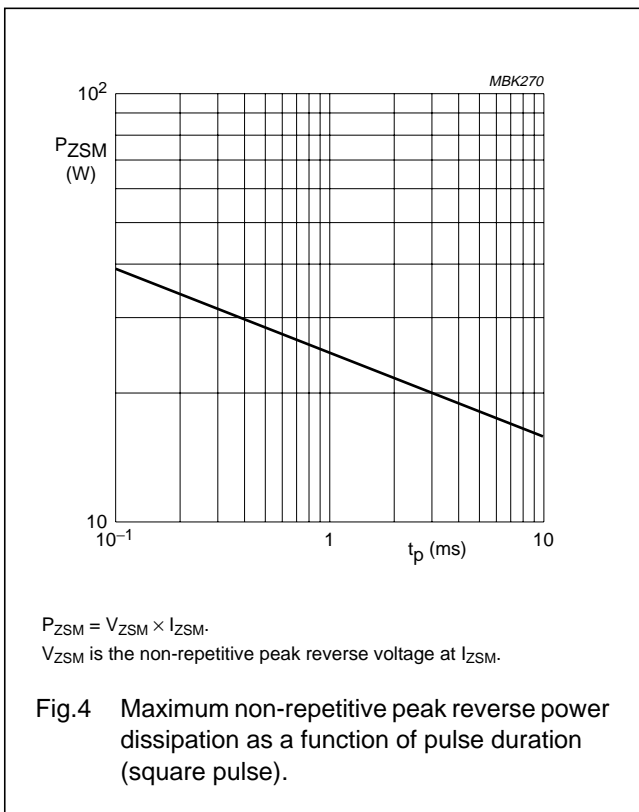
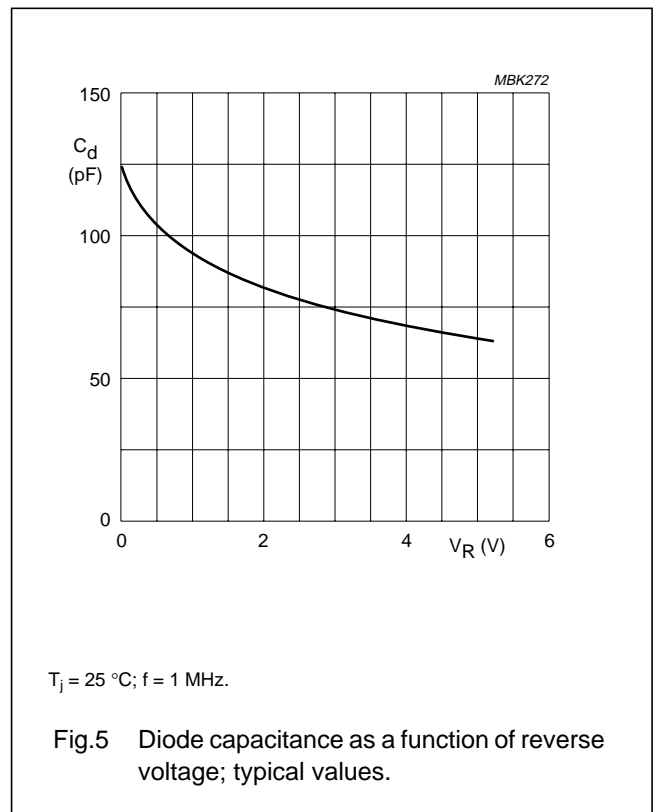


Fig.4 Maximum non-repetitive peak reverse power dissipation as a function of pulse duration (square pulse).

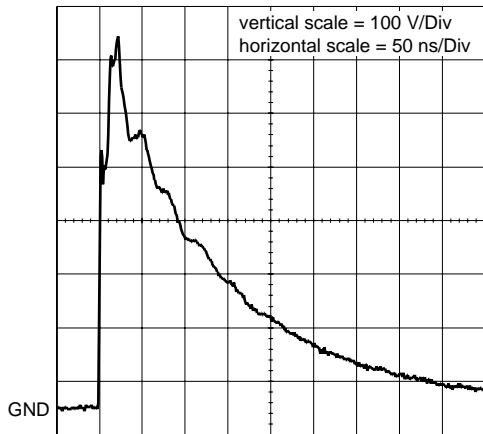
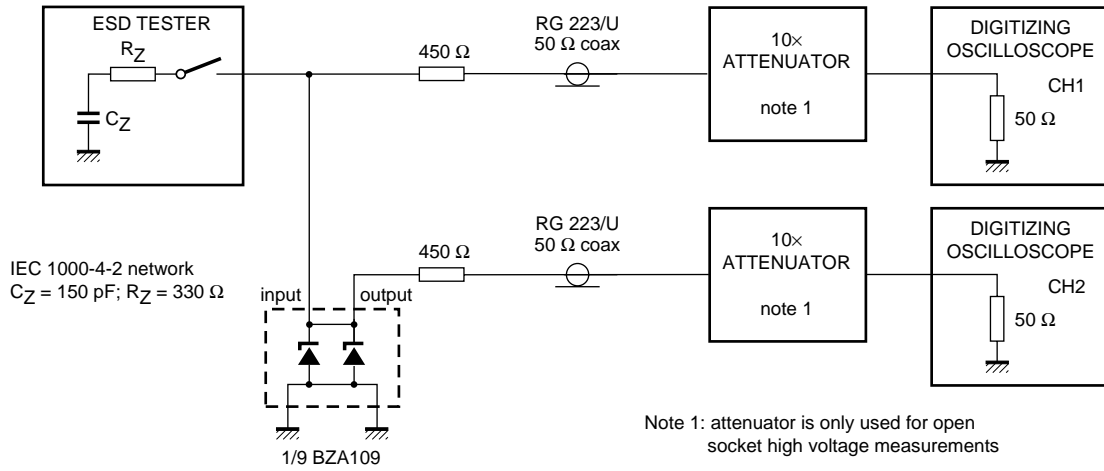


$T_j = 25\text{ }^\circ\text{C}$; $f = 1\text{ MHz}$.

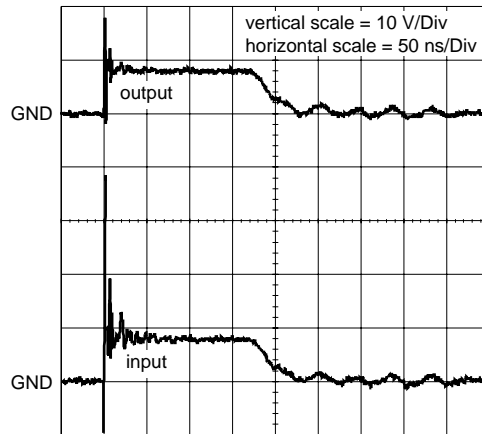
Fig.5 Diode capacitance as a function of reverse voltage; typical values.

9-fold ESD transient voltage suppressor

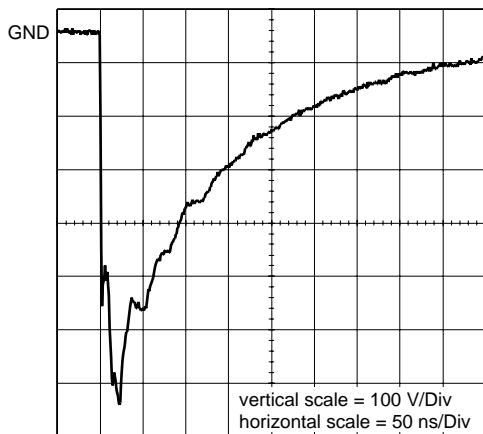
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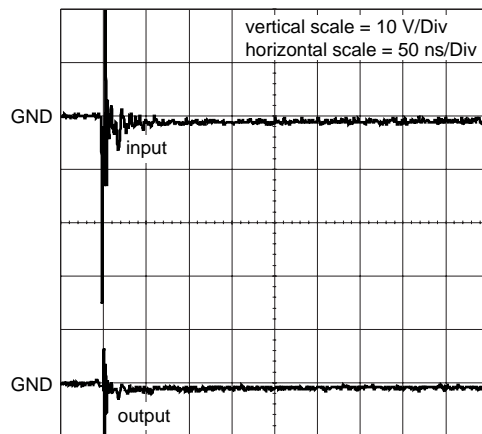
unclamped +1 kV ESD voltage waveform (IEC1000-4-2 network)



clamped +1 kV ESD voltage waveform (IEC1000-4-2 network)



unclamped -1 kV ESD voltage waveform (IEC1000-4-2 network)



clamped -1 kV ESD voltage waveform (IEC1000-4-2 network)

MBK273

Fig.6 ESD clamping test set-up and waveforms.

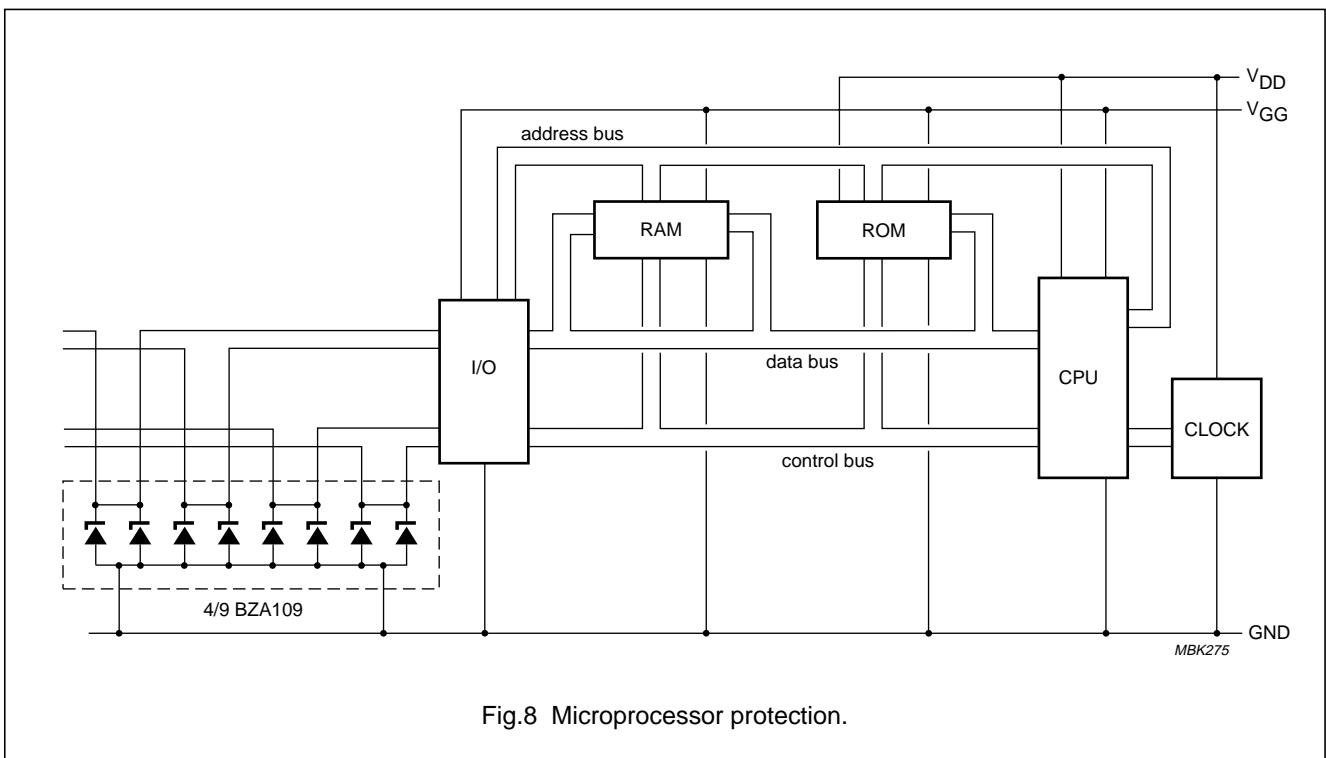
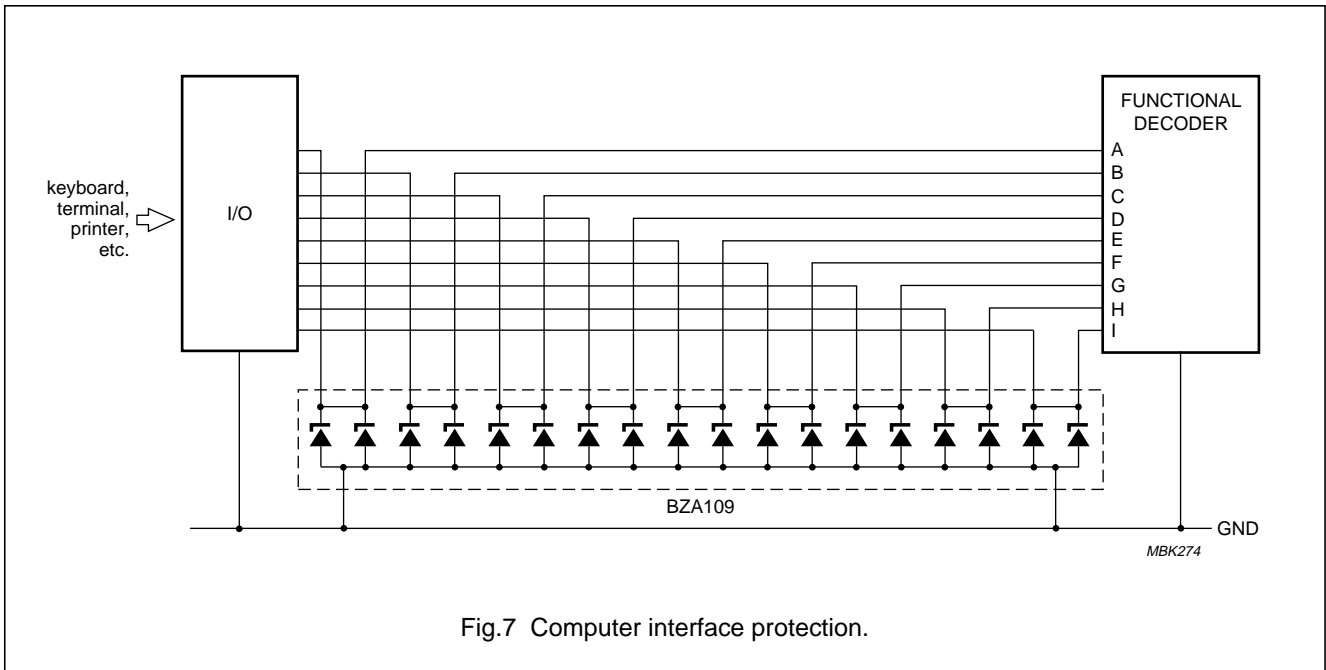
9-fold ESD transient voltage suppressor

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APPLICATION INFORMATION

Typical common anode application

A 9-fold transient suppressor in an SO20; SOT163-1 package makes it possible to protect nine separate lines using only one package. Two simplified examples are shown in Figs 7 and 8.



9-fold ESD transient voltage suppressor

BZA109

Device placement and printed-circuit board layout

Circuit board layout is of extreme importance in the suppression of transients. The clamping voltage of the BZA109 is determined by the peak transient current and the rate of rise of that current (di/dt). Since parasitic inductances can further add to the clamping voltage ($V = L di/dt$) the series conductor lengths on the printed-circuit board should be kept to a minimum. This includes the lead length of the suppression element.

In addition to minimizing conductor length the following printed-circuit board layout guidelines are recommended:

1. Place the suppression element close to the input terminals or connectors.
2. Keep parallel signal paths to a minimum.
3. Avoid running protection conductors in parallel with unprotected conductors.
4. Minimize all printed-circuit board loop areas including power and ground loops.
5. Minimize the length of the transient return path to ground.
6. Avoid using shared transient return paths to a common ground point.

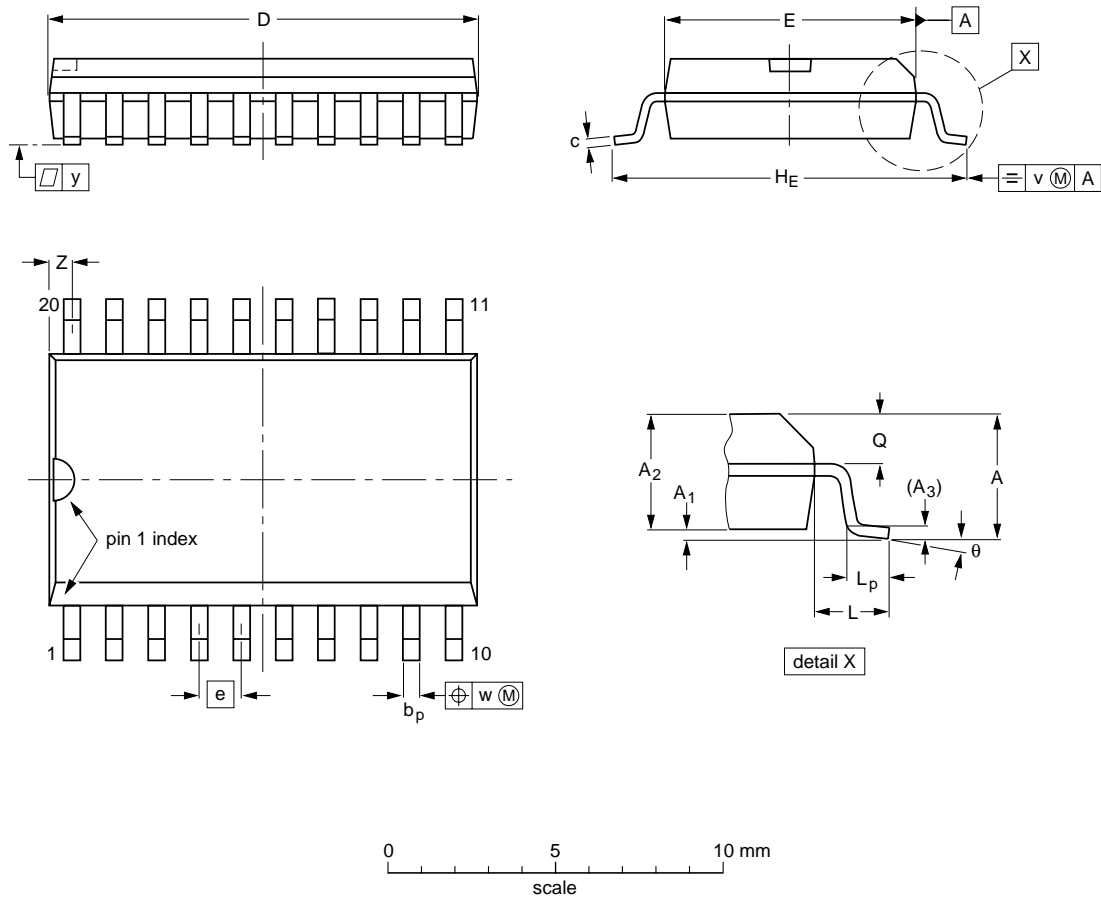
9-fold ESD transient voltage suppressor

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PACKAGE OUTLINE

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT163-1	075E04	MS-013AC			95-01-24 97-05-22

9-fold ESD transient voltage suppressor

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DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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NOTES

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